WHAT IS CLAIMED IS:

1. A heat dissipating device which dissipates heat from a heat generating object, comprising:

a heat receiving unit having a heat receiving surface and a heat dissipating surface in an opposite side of the heat receiving surface, the heat receiving surface being thermally connected to the heat generating object;

a heat transferring unit mounted on the heat dissipating surface of the heat receiving unit, transferring the heat received in the heat receiving surface, and diffusing the transferred heat to the heat dissipating surface; and

a heat dissipating unit mounted on the heat dissipating surface of the heat receiving unit, and dissipating the diffused heat.

2. A heat dissipating device according to claim 1, wherein the heat transferring unit extends along the heat dissipating surface of the heat receiving unit, a cross section of the heat transferring unit, which is along a direction crossing a longitudinal direction of the heat transferring unit, being flattened, and

a flat portion of the heat transferring unit in the flattened cross section is thermally connected to the heat dissipating surface of the heat receiving unit.

3. A heat dissipating device according to claim 2, wherein the heat transferring unit includes at least one heat pipe.

4. A heat dissipating device according to claim 1, wherein the heat dissipating unit includes a plurality of heat dissipating plates which are formed independently to each other.

5. A heat dissipating device according to claim 1, further comprising a heat conductive cover which is arranged between the heat transferring unit and the heat dissipating unit, and covers the heat transferring unit.

6. A heat dissipating device according to claim 5, wherein the heat conductive cover is configured by a plate, and includes a portion, which contacts the heat dissipating surface of the heat receiving unit, and a projecting portion, which projects from the heat dissipating surface and receives the heat transferring unit.

7. A heat dissipating device according to claim 6, wherein the heat transferring unit extends along the heat dissipating surface of the heat receiving unit, and

an outer surface of the heat transferring unit is thermally connected to the heat dissipating surface of the heat receiving unit and an inner surface of the projecting portion of the heat conductive cover.

8. A heat dissipating device according to claim 7, wherein a cross section of the heat transferring unit, which is along a direction crossing a longitudinal direction of the heat transferring unit, is flattened,

one of a pair of flat regions in the outer surface of the heat transferring unit is thermally connected to the heat dissipating surface of the heat receiving unit, and

another of the pair of flat regions in the outer surface of the heat transferring unit is thermally connected to the inner surface of the projecting portion of the heat conductive cover.

9. A heat dissipating device according to claim 8, wherein the heat transferring unit includes at least one heat pipe.

10. A heat dissipating device according to claim 6, wherein the heat dissipating unit includes a recess which fits on the projecting portion of the heat conductive cover.

11. A heat dissipating device according to claim 10, wherein the heat dissipating unit includes a plurality of heat dissipating plates which are formed independently to each other.

12. A heat dissipating device according to claim 5, wherein the heat transferring unit extends along the heat dissipating surface of the heat

receiving unit, a cross section of the heat transferring unit along a direction crossing a longitudinal direction of the heat transferring unit being flattened,

one of a pair of flat regions in an outer surface of the heat transferring unit is thermally connected to the heat dissipating surface of the heat receiving unit, and

another of the pair of flat regions in the outer surface of the heat transferring unit is thermally connected to the heat conductive cover.

13. A heat dissipating device according to claim 12, wherein the heat dissipating unit includes a plurality of heat dissipating plates which are formed independently to each other.

14. A heat dissipating device according to claim 12, wherein the heat transferring unit includes at least one heat pipe.

15. A heat dissipating device which dissipates heat from a heat generating object, comprising:

a heat receiving unit having a heat receiving surface and a heat dissipating surface in an opposite side of the heat receiving surface, the heat receiving surface being thermally connected to the heat generating object;

a heat transferring unit mounted on the heat receiving surface of the heat receiving unit with

excluding a part of the heat receiving surface thermally connected to the heat generating object, transferring the heat received in the heat receiving unit, and diffusing the transferred heat to the heat dissipating surface; and

a heat dissipating unit mounted on the heat dissipating surface of the heat receiving unit, and dissipating the diffused heat.

16. A heat dissipating device according to claim 15, wherein the heat transferring unit extends along the heat receiving surface of the heat receiving unit with excluding the part of the heat receiving surface thermally connected to the heat generating object,

a cross section of the heat transferring unit, which is along a direction crossing a longitudinal direction of the heat transferring unit, is flattened, and

a flat portion of the heat transferring unit in the flattened cross section is thermally connected to the heat receiving surface of the heat receiving unit with excluding the part of the heat receiving surface thermally connected to the heat generating object.

17. A heat dissipating device according to claim 16, wherein the heat transferring unit includes at least one heat pipe.

18. A heat dissipating device according to

claim 15, wherein the heat dissipating unit includes a plurality of heat dissipating plates which are formed independently to each other.

19. An electronic apparatus, comprising:

a circuit board including an electronic part generating heat;

a main body installing the circuit board; and

a heat dissipating device dissipating the heat from the electronic part,

the heat dissipating device including

a heat receiving unit having a heat receiving surface and a heat dissipating surface in an opposite side of the heat receiving surface, the heat receiving surface being thermally connected to the electronic part;

a heat transferring unit mounted on the heat dissipating surface of the heat receiving unit, transferring the heat received in the heat receiving unit, and diffusing the transferred heat to the heat dissipating surface; and

a heat dissipating unit mounted on the heat dissipating surface of the heat receiving unit, and dissipating the diffused heat.

20. An electronic apparatus according to claim 19, wherein the heat transferring unit extends along the heat dissipating surface of the heat receiving unit, a cross section of the heat transferring unit, which is

along a direction crossing a longitudinal direction of the heat transferring unit, being flattened, and

a flat portion of the heat transferring unit in the flattened cross section is thermally connected to the heat dissipating surface of the heat receiving unit.